XP-002318727

(C) WPI/Derwent

AN - 1999-199070 [17]
AP - JP19970203280 19970729
CPY - MITC
DC - A85 L03 P81 V07 V08
FS - CPI;GMPI;EPI
IC - B01J19/00 ; C01G11/02 ; C01G23/04 ; C08J3/20 ; C08K9/04 ; C08L101/00 ; G02F1/35
MC - A08-M09A A09-A03 A12-E01 A12-L03 L03-D L04-A
- V07-K10 V08-A04X
PA - (MITC) MITSUI PETROCHEM IND CO LTD
PN - JP11043556 A 19990216 DW199917 C08K9/04 007pp
PR - JP19970203280 19970729
XA - C1999-058263
XIC - B01J-019/00 ; C01G-011/02 ; C01G-023/04 ; C08J-003/20 ; C08K-009/04 ; C08L-101/00 ; G02F-001/35
XP - N1999-147074
AB - J11043556 NOVELTY - The resin material contains ultra small semiconductor particles, the surface of which undergoes a prior treatment by reaction with a compound containing one or more functional groups.
- DETAILED DESCRIPTION - An INDEPENDENT CLAIM is also included for the manufacturing method of surface treated semiconductor particle content resin material.
- USE - For electronic materials such as optical devices, refractive index adjusting devices, optical-electronic sensing element, phase conjugation wave generating unit, super lattice device, wavelength cut-off filter, magnetic recording, optical registration etc.
- ADVANTAGE - Enables uniform dispersion of the semiconductor ultra small particle in the resin material and the diameter and particle size distributions are controlled.
- (Dwg.0/4)
IW - SURFACE TREAT SEMICONDUCTOR PARTICLE CONTENT RESIN MATERIAL SEMICONDUCTOR PARTICLE TREAT COMPOUND CONTAIN ONE MORE FUNCTION GROUP PRIOR DISPERSE RESIN MATERIAL
IKW - SURFACE TREAT SEMICONDUCTOR PARTICLE CONTENT RESIN MATERIAL SEMICONDUCTOR PARTICLE TREAT COMPOUND CONTAIN ONE MORE FUNCTION GROUP PRIOR DISPERSE RESIN MATERIAL
NC - 001
OPD - 1997-07-29
ORD - 1999-02-16
PAW - (MITC) MITSUI PETROCHEM IND CO LTD
TI - Surface treated semiconductor particle content resin material - has semiconductor particles which are treated with compound containing one or more functional groups prior to dispersion in resin material